

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

**Claims 1-3. (Canceled).**

**claims 4-43. (Canceled).**

44. (New) A semiconductor device, comprising:

a semiconductor chip including a main surface and a back surface opposing to the main surface, a controlling circuit formed on the main surface, and a plurality of electrode pads formed on the main surface;

a capacitive element including a first electrode and a second electrode;

a first supporting body including a main surface and a back surface opposing to the main surface;

a second supporting body arranged next to the first supporting body, and including a main surface and a back surface opposing to the main surface wherein the main surface is located in a same side as the main surface of the first supporting body in a thickness direction of the first supporting body;

a wire connecting part connected with the first supporting body;

a plurality of leads arranged around the first supporting body;

a plurality of bonding wires electrically connected the electrode pads of the semiconductor chip with the leads, the wire connecting part and the main surface of the second supporting body; and

a resin sealing body sealing the semiconductor chip, the capacitive element, the first and second supporting bodies, the wire connecting part, a part of each of the leads, and the bonding wires;

wherein:

the back surface of the semiconductor chip is electrically connected with the controlling circuit;

the first and second supporting body are each comprised of a conductive material;

the semiconductor chip is adhered over the main surface of the first supporting body via a first adhesive material comprised of a non-conductive adhesive material such that the back surface of the semiconductor chip faces to the main surface of the first supporting body;

the first electrode of the capacitive element is adhered over the back surface of the first supporting body via a second adhesive material comprised of a conductive adhesive material; and

the second electrode of the capacitive element is adhered over the back surface of the second supporting body via the second adhesive material.

45. (New) A semiconductor device according to any one of claim 44, wherein

the resin sealing body includes an upper surface, an under surface, and a side surface; and

the leads include a first lead that projects from the under surface of the resin sealing body, and a second lead that projects from the upper surface of the resin sealing body.

46. (New) A semiconductor device according to claim 45, wherein

the first and the second lead each include an inner part located in an inside of the resin sealing body, and an outer part located in an outside of the resin sealing body;

the outer part of the first lead includes a first portion that projects from the under surface of the resin sealing body, and a second portion that bends in a direction along the under surface of the resin sealing body from the first portion; and

the outer part of the second lead includes a first portion that projects from the upper surface of the resin sealing body, and a second portion that bends in a direction along the upper surface of the resin sealing body from the first portion.

47. (New) A semiconductor device according to claim 46, wherein

the second portion of the first lead includes a portion of width wider than a width of the first portion of the first lead; and

the second portion of the second lead includes a portion of width wider than a width of the first portion of the second lead.

48. (New) A semiconductor device according to any claim 44, wherein

the supporting body is arranged so that the main surface of the supporting body is situated along a height direction of the resin sealing body.

49. (New) A semiconductor device according to any claim 44, wherein

the resin sealing body is formed in a cylinder shape which includes an upper surface and an under surface including a plane, and a side surface including a curved surface.

50. (New) A semiconductor device according to claim 44, wherein  
the resin sealing body is formed in a cylinder shape which includes an upper  
surface and an under surface including a plane, and a side surface including a  
curved surface; and  
the side surface of the resin sealing body includes a planar portion.

51. (New) A semiconductor device according to claim 44, wherein  
the resin sealing body is formed in a cylinder shape which includes an upper  
surface and an under surface including a plane, and a side surface including a  
curved surface; and  
the side surface of the resin sealing body has a planar portion spaced out  
from the upper surface of the resin sealing body.

52. (New) A semiconductor device according to claim 44, wherein  
the semiconductor chip is adhered over the first supporting body via a first  
binding material;  
the capacitive element is adhered over the first and the second supporting  
body via a second binding material; and  
the first binding material includes material having a fusing point which is  
higher than the second binding material.

53. (New) A semiconductor device according to claim 44, wherein  
the semiconductor chip is adhered over the first supporting body via a first  
binding material;

the capacitative element is adhered over the first and the second supporting body via a second binding material;

the first binding material includes a thermosetting material; and

the second binding material includes solder material.

54. (New) A semiconductor device according to claim 44, being built in an ignition device for mounting on a vehicle which operates an air bag based on a signal from an electronic control unit connected to an impact detection sensor.

55. (New) A semiconductor device according to any claim 44, wherein a volume of the capacitative element is larger than a volume of the semiconductor chip; and

wherein the second adhesive material is Pb-free solder material.